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Nest for Dicing, and Method and Apparatus for Cutting Tapeless Substrate Using the Same

ABSTRACT OF THE DISCLOSURE

A nest for dicing is arranged to support a substrate (102) including a chip (112) during a dicing process, the substrate (102) having a first side and a second side, wherein the second side of the substrate at least one contact associated with the chip (112). This nest for dicing comprises a nest main body (202) including a grid arrangement (212) which defines at least one opening that is arranged to receive the contact, and at least one alignment means (210) arranged to position the substrate (102) with respect to the nest main body (202). By means of using the nest, the substrate (102) can be securely held and efficiently diced to form individual integrated circuit chips without using any tape for adhesion.

(Figure 4)